01 July 2003



DI JWYZ	<u> </u>	Oll pariety 2		0.000
L Number	Hits	S arch Text	DB	Time stamp
1	4	216/58,83.ccls. and (diffraction adj (grate or	USPAT;	2003/06/30
		grating))	US-PGPUB;	10:34
			EPO; JPO;	
			DERWENT	
2	163	216/\$.ccls. and (diffraction adj (grate or grating))	USPAT;	2003/06/30
		*	US-PGPUB;	10:40
			EPO; JPO;	
			DERWENT	
3	6	(216/\$.ccls. and (diffraction adj (grate or grating)))	USPAT;	2003/06/30
		and (solar or photovoltaic)	US-PGPUB;	10:38
			EPO; JPO;	
			DERWENT	
4	. 42	(216/\$.ccls. and (diffraction adj (grate or grating)))	USPAT;	2003/06/30
		and (reactive adj ion adj etch\$3)	US-PGPUB;	10:41
			EPO; JPO;	
			DERWENT	
5	26	216/\$.ccls. and ((diffraction adj (grate or grating))	USPAT;	2003/06/30
		with (transmi\$7 or transparent))	US-PGPUB;	10:41
			EPO; JPO;	•
	_		DERWENT	
6	7	(216/\$.ccls. and ((diffraction adj (grate or grating))	USPAT;	2003/06/30
		with (transmi\$7 or transparent))) and (reactive adj	US-PGPUB;	11:25
		ion adj etch\$3)	EPO; JPO;	
_			DERWENT	
7	343	136/\$.ccls. and (ion adj implantation)	USPAT;	2003/06/30
			US-PGPUB;	11:25
			EPO; JPO;	
8	41	(136/\$.ccls. and (ion adj implantation)) and	DERWENT USPAT;	2003/06/30
0	, 71	(diffraction or diffractive)	US-PGPUB;	11:25
		(diffraction of diffractive)	EPO; JPO;	11.23
			DERWENT	
9	3	(136/\$.ccls. and (ion adj implantation)) and	USPAT;	2003/06/30
•		((diffraction or diffractive) adj grating)	US-PGPUB;	12:03
y.	·		EPO; JPO;	
			DERWENT	
10	27	136/\$.ccls. and ((rie or (reactive adj ion adj etch\$3))	USPAT;	2003/06/30
		with (contamin\$7 or clean or remov\$3))	US-PGPUB;	12:08
	·	• •	EPO; JPO;	
			DERWENT	
11	0	216/\$.ccls. and ((rie or (reactive adj ion adj etch\$3))	USPAT;	2003/06/30
		with (contamin\$7 or clean\$3))	US-PGPUB;	12:08
,			EPO; JPO;	
,			DERWENT	
13	27	136/\$.ccls. and ((rie or (reactive adj ion adj etch\$3))	USPAT;	2003/06/30
		with (contamin\$7 or clean\$3 or remov\$3))	US-PGPUB;	12:08
			EPO; JPO;	
			DERWENT	
12	93	216/\$.ccls. and ((ri or (reactive adj ion adj etch\$3))	USPAT;	2003/06/30
,		with (contamin\$7 or clean\$3))	US-PGPUB;	12:18
		,	EPO; JPO;	
	l		DERWENT	

14	76	(216/\$.ccls. and ((rie or (reactive adj ion adj	USPAT;	2003/06/30
		tch\$3)) with (contamin\$7 or clean\$3))) and silicon	US-PGPUB; EPO; JPO;	12:15
			DERWENT	1.1
15	17	(216/\$.ccls. and ((rie or (reactiv adj ion adj	USPAT;	2003/06/30
		etch\$3)) with (contamin\$7 or clean\$3))) not silicon	US-PGPUB;	12:16
			EPO; JPO;	,
		•	DERWENT	
16	76	(216/\$.ccls. and ((rie or (reactive adj ion adj	USPAT;	2003/06/30
		etch\$3)) with (contamin\$7 or clean\$3))) not	US-PGPUB;	12:16
		((216/\$.ccls. and ((rie or (reactive adj ion adj	EPO; JPO;	
		etch\$3)) with (contamin\$7 or clean\$3))) not silicon)	DERWENT	
17	0	((216/\$.ccls. and ((rie or (reactive adj ion adj	USPAT;	2003/06/30
		etch\$3)) with (contamin\$7 or clean\$3))) not	US-PGPUB;	12:19
		((216/\$.ccls. and ((rie or (reactive adj ion adj	EPO; JPO;	
		etch\$3)) with (contamin\$7 or clean\$3))) not silicon))	DERWENT	
*		and ((clean\$5 or contamin\$7) with ((potassium adj		
	100	hydroxide) or koh! or (wet adj chemical adj etch\$3)))	I I CD A T.	2002/0//20
18	180	216/\$.ccls. and ((rie or (reactive adj ion adj etch\$3))	USPAT;	2003/06/30
		with (contamin\$7 or clean\$3 or damag\$3))	US-PGPUB;	12:19
			EPO; JPO; DERWENT	,
19 ·	33	(216/\$.ccls. and ((rie or (reactive adj ion adj	USPAT;	2003/06/30
19	33	etch\$3)) with (contamin\$7 or clean\$3 or damag\$3)))	US-PGPUB;	12:19
		not silicon	EPO; JPO;	12.19
		not sineon	DERWENT	
20	147	(216/\$.ccls. and ((rie or (reactive adj ion adj	USPAT;	2003/06/30
		etch\$3)) with (contamin\$7 or clean\$3 or damag\$3)))	US-PGPUB;	12:19
		not ((216/\$.ccls. and ((rie or (reactive adj ion adj	EPO; JPO;	
		etch\$3)) with (contamin\$7 or clean\$3 or damag\$3)))	DERWENT	
		not silicon)		
21	0	((216/\$.ccls. and ((rie or (reactive adj ion adj	USPAT;	2003/06/30
		etch\$3)) with (contamin\$7 or clean\$3 or damag\$3)))	US-PGPUB;	12:19
		not ((216/\$.ccls. and ((rie or (reactive adj ion adj	EPO; JPO;	
		etch\$3)) with (contamin\$7 or clean\$3 or damag\$3)))	DERWENT	
		not silicon)) and ((clean\$5 or contamin\$7) with		
		((potassium adj hydroxide) or koh! or (wet adj		
	·	chemical adj etch\$3)))	l <u>.</u> _	
22	2	((216/\$.ccls. and ((rie or (reactive adj ion adj	USPAT;	2003/06/30
		etch\$3)) with (contamin\$7 or clean\$3 or damag\$3)))	US-PGPUB;	12:19
		not ((216/\$.ccls. and ((rie or (reactive adj ion adj	EPO; JPO;	
		etch\$3)) with (contamin\$7 or clean\$3 or damag\$3)))	DERWENT	
		not silicon)) and ((clean\$5 or contamin\$7 or	1	
		damag\$4) with ((potassium adj hydroxide) or koh! or		
		(wet adj chemical adj etch\$3)))	I	J